

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

**(19) World Intellectual Property Organization
International Bureau**



(43) International Publication Date
30 June 2005 (30.06.2005)

PCT

(10) International Publication Number
WO 2005/059549 A1

(51) International Patent Classification⁷: G01N 33/53
27/26, 27/447, C12M 1/36, C12P 19/34

[KR/KR]; 501, Grandciel Villa, Bangbae 4-Dong, Seocho-Ku, Seoul, 137-064 (KR). HUR, Dae Sung [KR/KR];

(21) International Application Number: PCT/KR2004/003337

110-188, Keumhwa 4K, Hayang-Eup, Kyungsan-Si, Kyungsangbuk-Do, 712-905 (KR). **CHUNG, Chanil** [KR/KR]; 106-2201, Samsung Raemian Apartment, Naeson-Dong, Uiwang-Si, Kyunggi-Do, 437-080 (KR). **PARK, Jun Ha** [KR/KR]; 803-1504, Byukjukgol Doosan Apartment, Youngtong-Dong, Paldal-Ku, Suwon-Si, Kyunggi-Do, 442-470 (KR). **JO, Han Sang** [KR/KR]; 103-405, Dream Village Life Apartment, Kuiin-Dong, Dongan-Ku, Anyang-Si, Kyunggi-Do, 431-708 (KR).

(22) International Filing Date: 17 December 2004 (17.12.2004)

Agent: KIM, Sun-young; Korea Coal Center, 10th Floor, 80-6, Susong-Dong, Chongro-Ku, Seoul, 110-727 (KR).

(25) Filing Language: Korean

Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH,

(30) Priority Data:
10-2003-0093443

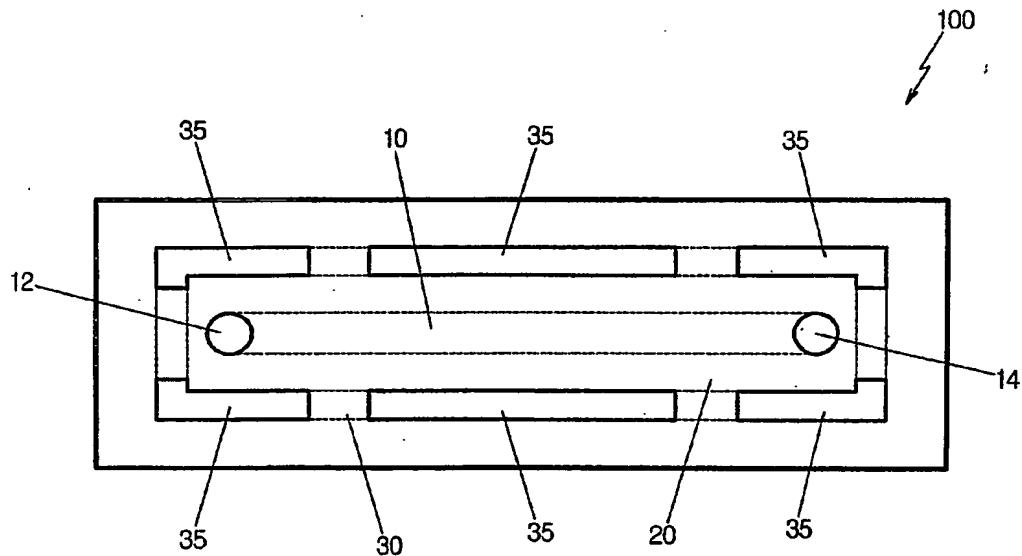
(71) **Applicant (for all designated States except US):** Digital Bio Technology [KR/KR]; Seoul National University In-

stitute of Advanced Machinery 1304, San 36-1 Shinlim,
Kwanak, Seoul, 151-742 (KR).

(72) Inventors; and
(75) Inventors/Applicants (for US only): CHANG, Jun Keun

(54) Title: METHOD FOR BONDING PLASTIC MICRO CHIP

[Continued on next page]



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(57) Abstract: Disclosed is a method of bonding upper and lower substrates for manufacturing a plastic micro chip comprising the upper substrate, the lower substrate and a sample filling space having a predetermined height for filling a sample between the upper and lower substrates. According to the method, the upper and lower substrates are bonded by introducing an organic solvent between the upper and lower substrates. In addition, the invention provides a method of manufacturing a micro chip using the method and a micro chip manufactured according to the method. According to the invention, it is possible to easily and precisely bond the upper and lower substrates of the plastic micro chip.



PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(84) **Designated States (unless otherwise indicated, for every kind of regional protection available):** ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,

Published:

— with international search report

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